Memory Summary For DESKTOP-8K547KV

Number of Memory Devices: 3 Total Physical Memory: 6103 MB (6144 MB)

 Total Available Physical Memory: 2370 MB

 Memory Load: 61%

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| **Item** | **Slot #1** | **Slot #2** | **Slot #3** | **Slot #4** |
| Ram Type | DDR3 | DDR3 | DDR3 | Not Populated |
| Maximum Clock Speed (MHz) | 667 (JEDEC) | 667 (JEDEC) | 667 (JEDEC) |  |
| Maximum Transfer Speed (MHz) | DDR3-1333 | DDR3-1333 | DDR3-1333 |  |
| Maximum Bandwidth (MB/s) | PC3-10600 | PC3-10600 | PC3-10600 |  |
| Memory Capacity (MB) | 2048 | 2048 | 2048 |  |
| DIMM Temperature | N/A | N/A | N/A |  |
| Jedec Manufacture Name | SK Hynix | SK Hynix | SK Hynix |  |
| Search Amazon.com | Search! | Search! | Search! |  |
| SPD Revision | 1.0 | 1.0 | 1.0 |  |
| Registered | No | No | No |  |
| ECC | No | No | No |  |
| On-Die ECC | No | No | No |  |
| DIMM Slot # | 1 | 2 | 3 |  |
| Manufactured | Week 38 of Year 2010 | Week 38 of Year 2010 | Week 38 of Year 2010 |  |
| Module Part # | HMT125U6DFR8C-H9 | HMT125U6DFR8C-H9 | HMT125U6DFR8C-H9 |  |
| Module Revision | 0x4E30 | 0x4E30 | 0x4E30 |  |
| Module Serial # | 0x206081FD | 0x209081FE | 0x205081FD |  |
| Module Manufacturing Location | 1 | 1 | 1 |  |
| # of Row Addressing Bits | 14 | 14 | 14 |  |
| # of Column Addressing Bits | 10 | 10 | 10 |  |
| # of Banks | 8 | 8 | 8 |  |
| # of Ranks | 2 | 2 | 2 |  |
| Device Width in Bits | 8 | 8 | 8 |  |
| Bus Width in Bits | 64 | 64 | 64 |  |
| Module Voltage | 1.5V | 1.5V | 1.5V |  |
| CAS Latencies Supported | 6 7 8 9 | 6 7 8 9 | 6 7 8 9 |  |
| Timings @ Max Frequency (JEDEC) | 9-9-9-24 | 9-9-9-24 | 9-9-9-24 |  |
| Maximum frequency (MHz) | 667 | 667 | 667 |  |
| Maximum Transfer Speed (MHz) | DDR3-1333 | DDR3-1333 | DDR3-1333 |  |
| Maximum Bandwidth (MB/s) | PC3-10600 | PC3-10600 | PC3-10600 |  |
| Minimum Clock Cycle Time, tCK (ns) | 1.500 | 1.500 | 1.500 |  |
| Minimum CAS Latency Time, tAA (ns) | 13.125 | 13.125 | 13.125 |  |
| Minimum RAS to CAS Delay, tRCD (ns) | 13.125 | 13.125 | 13.125 |  |
| Minimum Row Precharge Time, tRP (ns) | 13.125 | 13.125 | 13.125 |  |
| Minimum Active to Precharge Time, tRAS (ns) | 36.000 | 36.000 | 36.000 |  |
| Minimum Row Active to Row Active Delay, tRRD (ns) | 6.000 | 6.000 | 6.000 |  |
| Minimum Auto-Refresh to Active/Auto-Refresh Time, tRC (ns) | 49.125 | 49.125 | 49.125 |  |
| Minimum Auto-Refresh to Active/Auto-Refresh Command Period, tRFC (ns) | 110.000 | 110.000 | 110.000 |  |
|  |  |  |  |  |
| DDR3 Specific SPD Attributes |  |  |  |  |
| Write Recovery Time, tWR (ns) | 15.000 | 15.000 | 15.000 |  |
| Internal Write to Read Command Delay, tWTR (ns) | 7.500 | 7.500 | 7.500 |  |
| Internal Read to Precharge Command Delay, tRTP (ns) | 7.500 | 7.500 | 7.500 |  |
| Minimum Four Activate Window Delay, tFAW (ns) | 30.000 | 30.000 | 30.000 |  |
| Maximum Activate Window in units of tREFI | 0 | 0 | 0 |  |
| RZQ / 6 Supported | Yes | Yes | Yes |  |
| RZQ / 7 Supported | Yes | Yes | Yes |  |
| DLL-Off Mode Supported | Yes | Yes | Yes |  |
| Maximum Operating Temperature Range (C) | 0-95 | 0-95 | 0-95 |  |
| Refresh Rate at Extended Operating Temperature Range | 2X | 2X | 2X |  |
| Auto-self Refresh Supported | Yes | Yes | Yes |  |
| On-die Thermal Sensor Readout Supported | No | No | No |  |
| Partial Array Self Refresh Supported | No | No | No |  |
| Thermal Sensor Present | No | No | No |  |
| Non-standard SDRAM Type | Standard Monolithic | Standard Monolithic | Standard Monolithic |  |
| Maxium Activate Count (MAC) |  |  |  |  |
| Module Type | UDIMM | UDIMM | UDIMM |  |
| Module Height (mm) | 30 | 30 | 30 |  |
| Module Thickness (front), (mm) | 2 | 2 | 2 |  |
| Module Thickness (back), (mm) | 2 | 2 | 2 |  |
| Module Width (mm) | 133.5 | 133.5 | 133.5 |  |
| Reference Raw Card Used | Raw Card B Rev. 0 | Raw Card B Rev. 0 | Raw Card B Rev. 0 |  |
| DRAM Manufacture | SK Hynix | SK Hynix | SK Hynix |  |